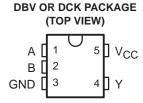
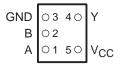
SCES213O - APRIL 1999 - REVISED SEPTEMBER 2003

- Available in the Texas Instruments
 NanoStar[™] and NanoFree[™] Packages
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 3.6 ns at 3.3 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



YEA, YEP, YZA, OR YZP PACKAGE (BOTTOM VIEW)



description/ordering information

This single 2-input positive-NOR gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G02 performs the Boolean function $Y = \overline{A + B}$ or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

TA	PACKAGE†	PACKAGE [†]			
	NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA		SN74LVC1G02YEAR		
	NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free)	Reel of 3000	SN74LVC1G02YZAR	СВ	
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP		SN74LVC1G02YEPR	0b_	
−40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		SN74LVC1G02YZPR	1	
	SOT (SOT-23) – DBV	Reel of 3000	SN74LVC1G02DBVR	COS	
	301 (301-23) – DBV	Reel of 250	SN74LVC1G02DBVT	C02_	
	SOT (SC-70) – DCK	Reel of 3000	SN74LVC1G02DCKR	СВ	
	301 (30-70) - DON	Reel of 250	SN74LVC1G02DCKT	CD_	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site. YEA/YZA,YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

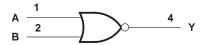
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TEXAS INSTRUMENTS
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FUNCTION TABLE

INP	JTS	OUTPUT
Α	В	Y
Н	Χ	L
X	Н	L
L	L	Н

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V_{CC}	
Voltage range applied to any output in the high-impedance or power-off state, V _O (see Note 1)	0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, $V_{\mbox{\scriptsize O}}$	
(see Notes 1 and 2)	-0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Continuous output current, IO	
Continuous current through V _{CC} or GND	
Package thermal impedance, θ _{JA} (see Note 3): DBV package	
DCK package	
YEA/YZA package	
YEP/YZP package	
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The value of $V_{\hbox{CC}}$ is provided in the recommended operating conditions table.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V	Supply voltage	Operating	1.65	5.5	V
VCC	Supply voltage	Data retention only	1.5		V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		
\/	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
VIH	nigh-level input voltage	V _{CC} = 3 V to 3.6 V	2		v
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0.7 × V _{CC}		
		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}	
\/	Low level input valtage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
VIL	/IL Low-level input voltage	V _{CC} = 3 V to 3.6 V		0.8	V
		V _{CC} = 4.5 V to 5.5 V		0.3 × V _{CC}	
٧ _I	Input voltage		0	5.5	V
۷o	Output voltage		0	VCC	V
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-8	
loh	High-level output current			-16	mA
				-24	
		V _{CC} = 4.5 V		-32	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		8	
I_{OL}	Low-level output current	V3V		16	mA
		VCC = 3 V		24	
		V _{CC} = 4.5 V		32	
		$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}, 2.5 \text{ V} \pm 0.2 \text{ V}$		20	
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V
		$V_{CC} = 5 V \pm 0.5 V$		5	
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAF	RAMETER	TEST CONDITIONS	VCC	MIN	TYP [†]	MAX	UNIT		
		$I_{OH} = -100 \mu\text{A}$	1.65 V to 5.5 V	V _{CC} -0.1					
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2					
		$I_{OH} = -8 \text{ mA}$	2.3 V	1.9			.,		
VOH		$I_{OH} = -16 \text{ mA}$	2./	2.4			V		
		$I_{OH} = -24 \text{ mA}$	3 V	2.3					
		I _{OH} = -32 mA	4.5 V	3.8					
		I _{OL} = 100 μA	1.65 V to 5.5 V			0.1			
		I _{OL} = 4 mA	1.65 V			0.45).45		
		I _{OL} = 8 mA	2.3 V	0.3			. ,		
VOL		I _{OL} = 16 mA	3 V			0.4	V		
		I _{OL} = 24 mA	3 V			0.55			
		I _{OL} = 32 mA	4.5 V			0.55			
Ц	A or B inputs	V _I = 5.5 V or GND	0 to 5.5 V			±5	μА		
l _{off}		V_I or $V_O = 5.5 V$	0			±10	μΑ		
Icc		$V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$	1.65 V to 5.5 V			10	μΑ		
Δlcc		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 5.5 V			500	μΑ		
Ci		$V_I = V_{CC}$ or GND	3.3 V		4		pF		

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =		V _{CC} =		V _{CC} = ± 0.		V _{CC} ± 0.		UNIT
	(INPOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
tpd	A or B	Y	1.9	7.2	0.8	4.4	0.8	3.6	0.8	3.4	ns

switching characteristics over recommended operating free-air temperature range, C_L = 30 pF or 50 pF (unless otherwise noted) (see Figure 2)

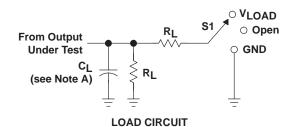
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	A or B	Υ	2.8	8	1.2	5.5	1	4.5	1	4	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	V _{CC} = 5 V	UNIT
		TEST CONDITIONS	TYP	TYP	TYP TYP		UNIT
C _{pd}	Power dissipation capacitance	f = 10 MHz	23	23	23	25	pF

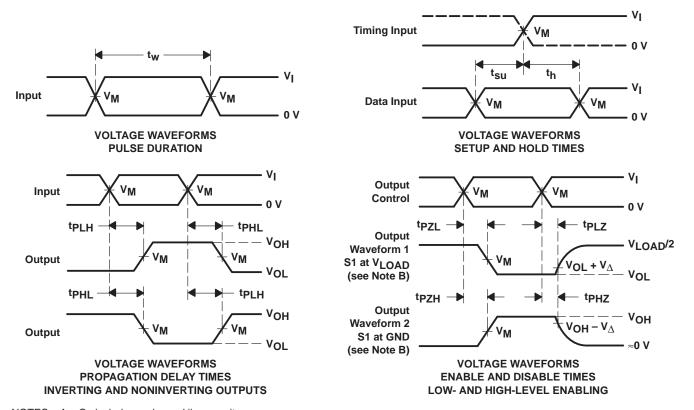


PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

.,	INF	PUTS		V		_	.,
VCC	٧ _I	t _r /t _f	VM	VLOAD	CL	RL	$oldsymbol{V}_\Delta$
1.8 V ± 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	15 pF	1 M Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤ 2 ns	V _{CC} /2	2×V _{CC}	15 pF	1 M Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	15 pF	1 M Ω	0.3 V
5 V \pm 0.5 V	VCC	≤2.5 ns	V _{CC} /2	2×V _{CC}	15 pF	1 M Ω	0.3 V



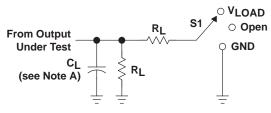
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



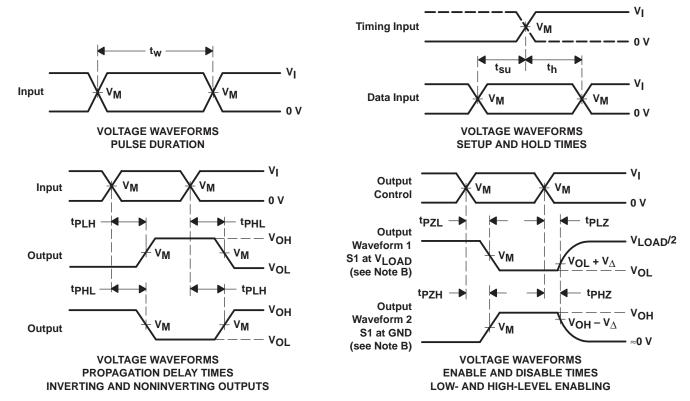
PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL tPLZ/tPZL	Open V _{LOAD}
tPHZ/tPZH	GND

LOAD CIRCUIT

.,	INF	PUTS	.,		•	_	.,
VCC	٧ _I	t _r /t _f	VM	VLOAD	CL	RL	$v_{\scriptscriptstyle\Delta}$
1.8 V \pm 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤ 2 ns	V _{CC} /2	2×VCC	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V \pm 0.5 V	VCC	≤2.5 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.3 V



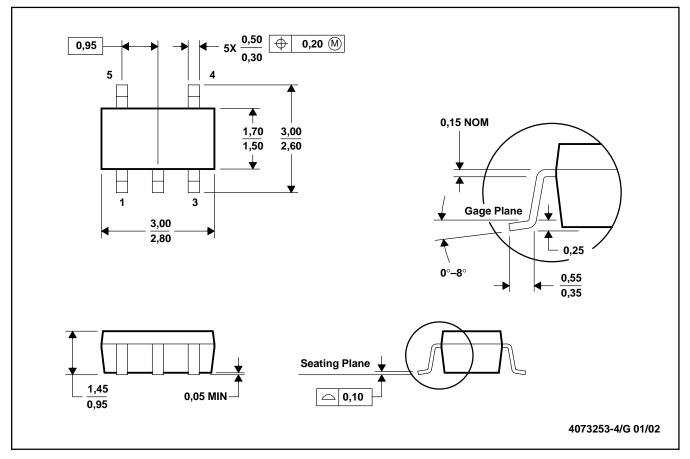
- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tplH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE

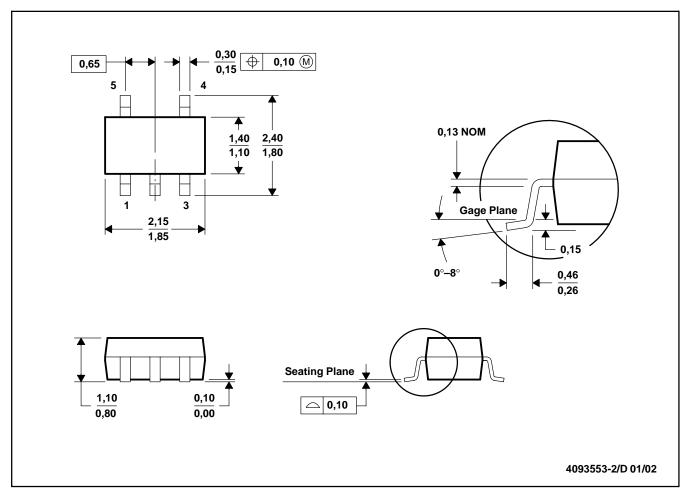


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-178

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

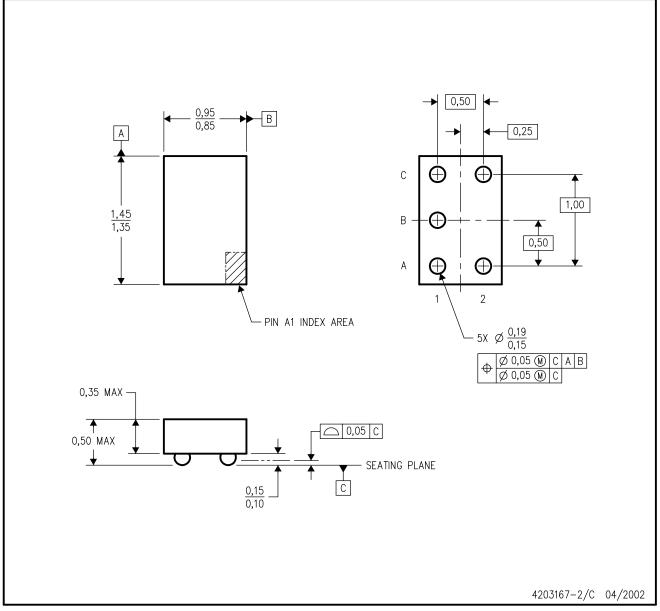
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-203

YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

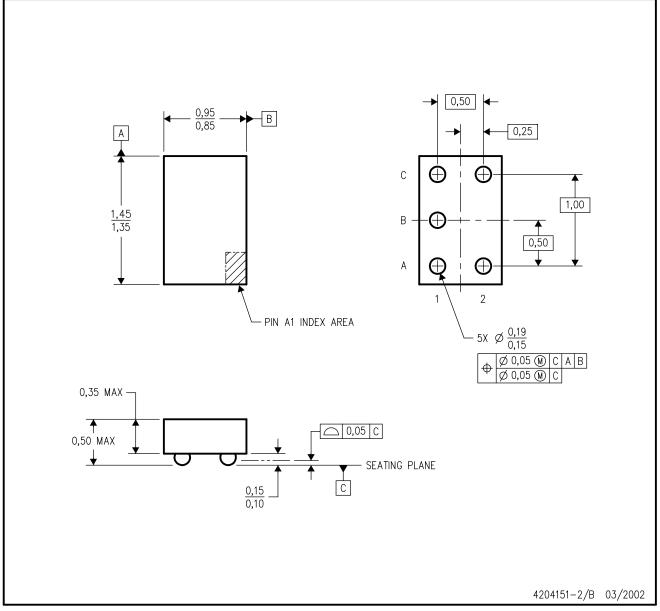
- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

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YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

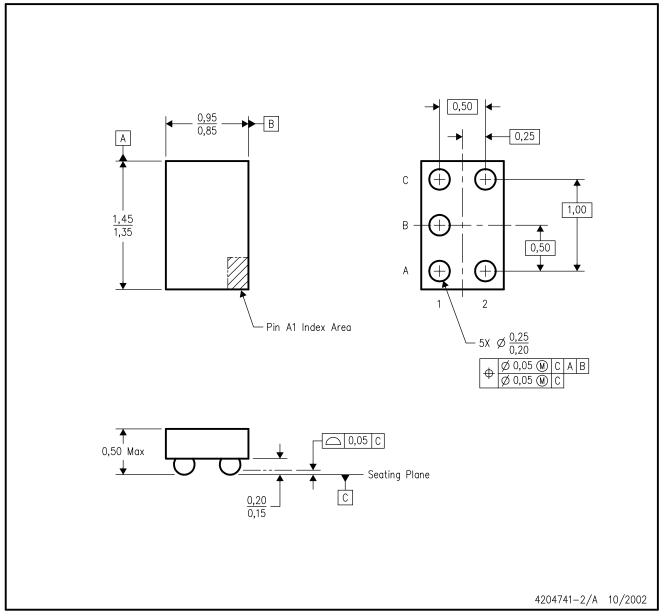
- B. This drawing is subject to change without notice.
- C. NanoFree $^{\text{TM}}$ package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

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YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

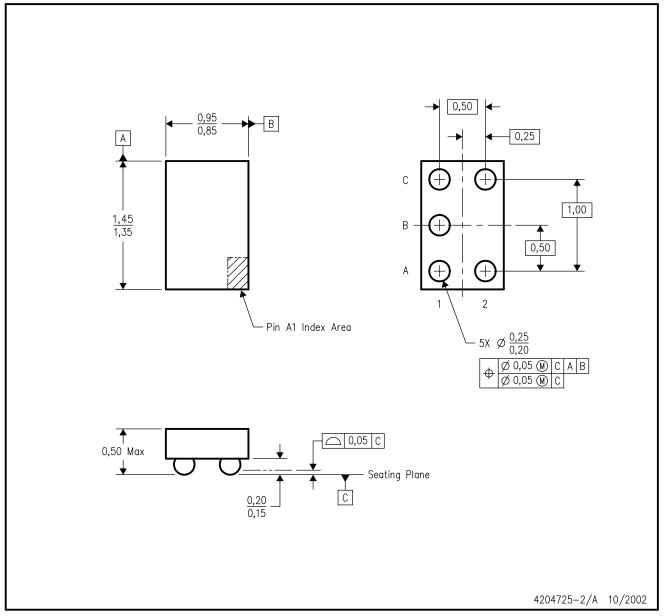
- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

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YEP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

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